Special Issue

Design, Fabrication, Testing of MEMS/NEMS

Message from the Guest Editors

Here, we would like to introduce the special issue of "Design, Fabrication, Testing of MEMS/NEMS" and encourage our colleagues to contribute their excellent work to this Special Issue. This Special Issue aims to highlight recent novel progresses in cutting-edge MEMS device technologies, including original research articles and topical reviews in the scope of materials, design and fabrication technologies, characterization methods, packaging and microsystem integration solutions. The topics of this Special Issue include, but are not limited to:

- Novel functional MEMS materials:
- Innovative MEMS mechanical and chemical sensors;
- Biological devices for wearable healthcare systems;
- Optical and quantum MEMS devices and systems;
- RF MEMS for telecommunication systems;
- MEMS devices for self-powered systems;
- Micro/nano fabrication process and integration;
- MEMS packaging and reliability issues.

Guest Editors

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Dr. Chen Liu

Deadline for manuscript submissions

closed (30 December 2022)



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About the Journal

Message from the Editor-in-Chief

You are invited to contribute research articles or comprehensive reviews for consideration and publication in *Micromachines* (ISSN 2072-666X). *Micromachines* is published in the open access format. Research articles, reviews and other contents are released on the internet immediately after acceptance. The scientific community and the general public have unlimited free access to the content as soon as it is published. As an open access journal, *Micromachines* is supported by the authors or their institutes by payment of article processing charges (APC) for accepted papers. We are pleased to welcome you as our authors.

Editor-in-Chief

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